

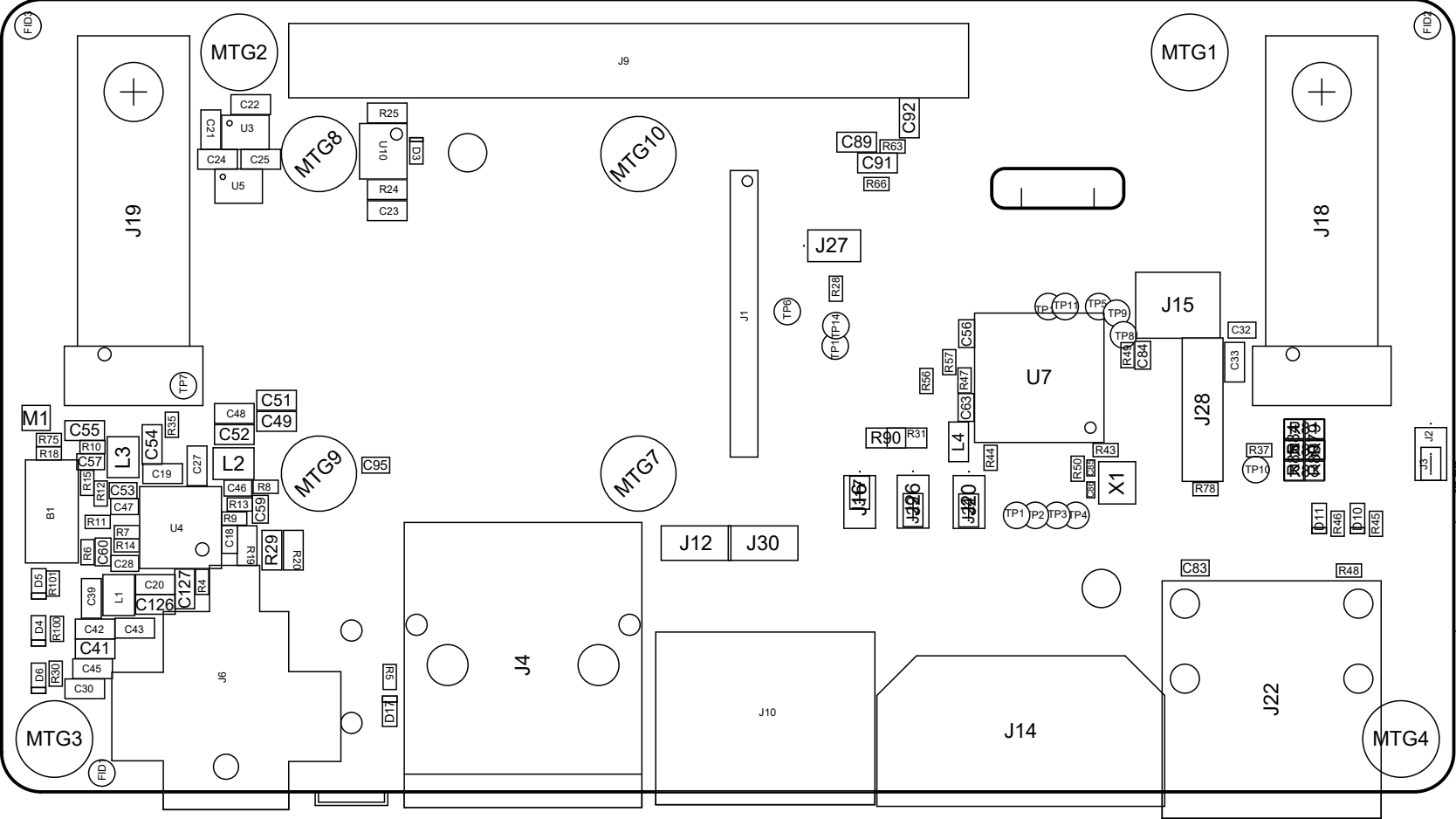
ASSEMBLY NOTES:

Assembly shall conform to IPC-A-610 Class 2.  
Assembly shall conform with RoHS Directive 2011/65/EU.  
Components shall be placed according to the associated CPL and BOM documents.  
Lead-free SAC305 solder shall be used.  
Reflow profile shall comply with J-STD-20C Lead-Free Reflow Profile.  
BGA components shall be 100% checked with x-ray for solder bridges after reflow.  
Finished assemblies shall be removed from panel prior to delivery.

Notes:

- 1
- Note 1: Receptacles for CM4 and J1 are the same (3pcs)
- 2
- Note 2: Last page is withot CM4
- 3
- Note 3

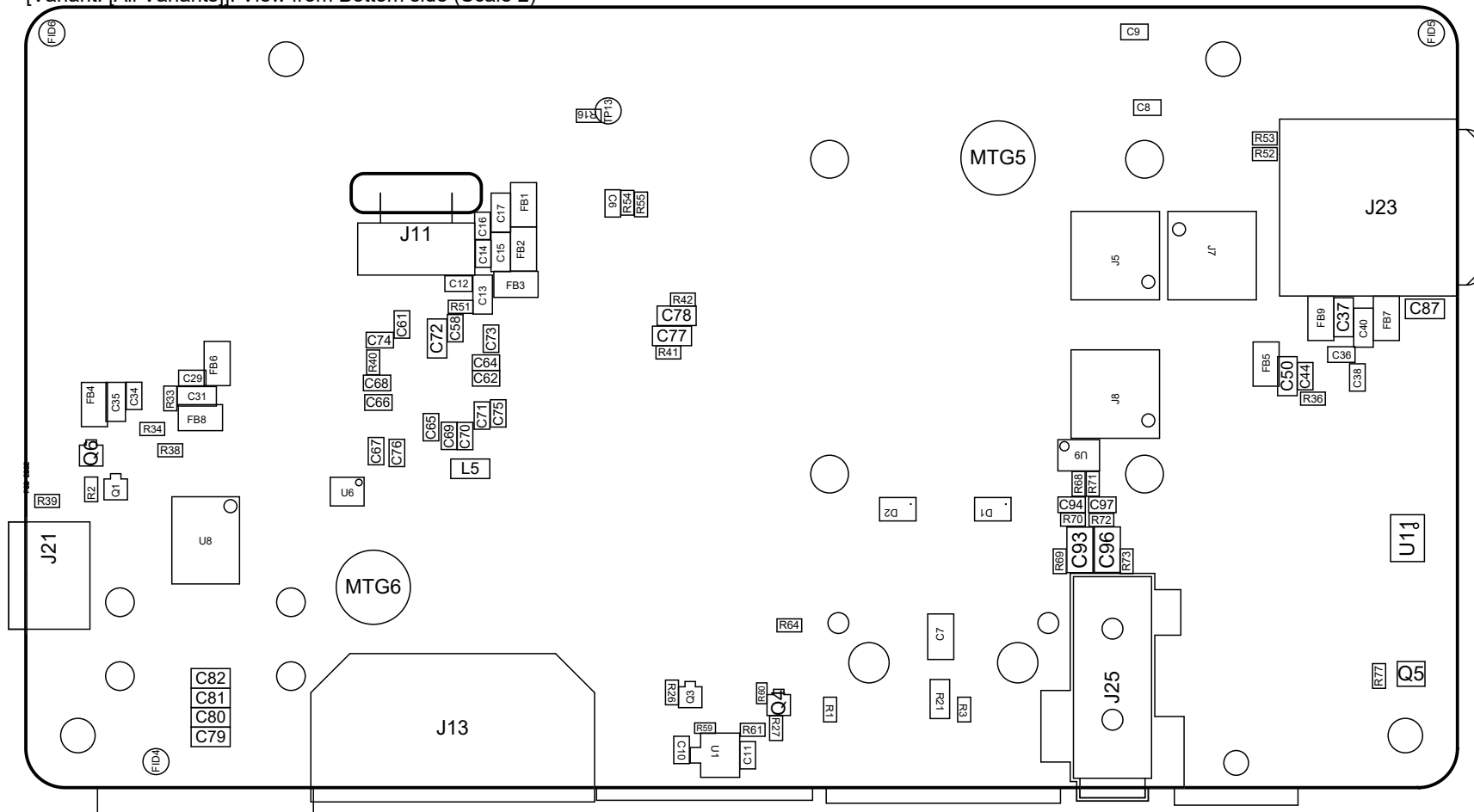
View from Top side (Scale 2)




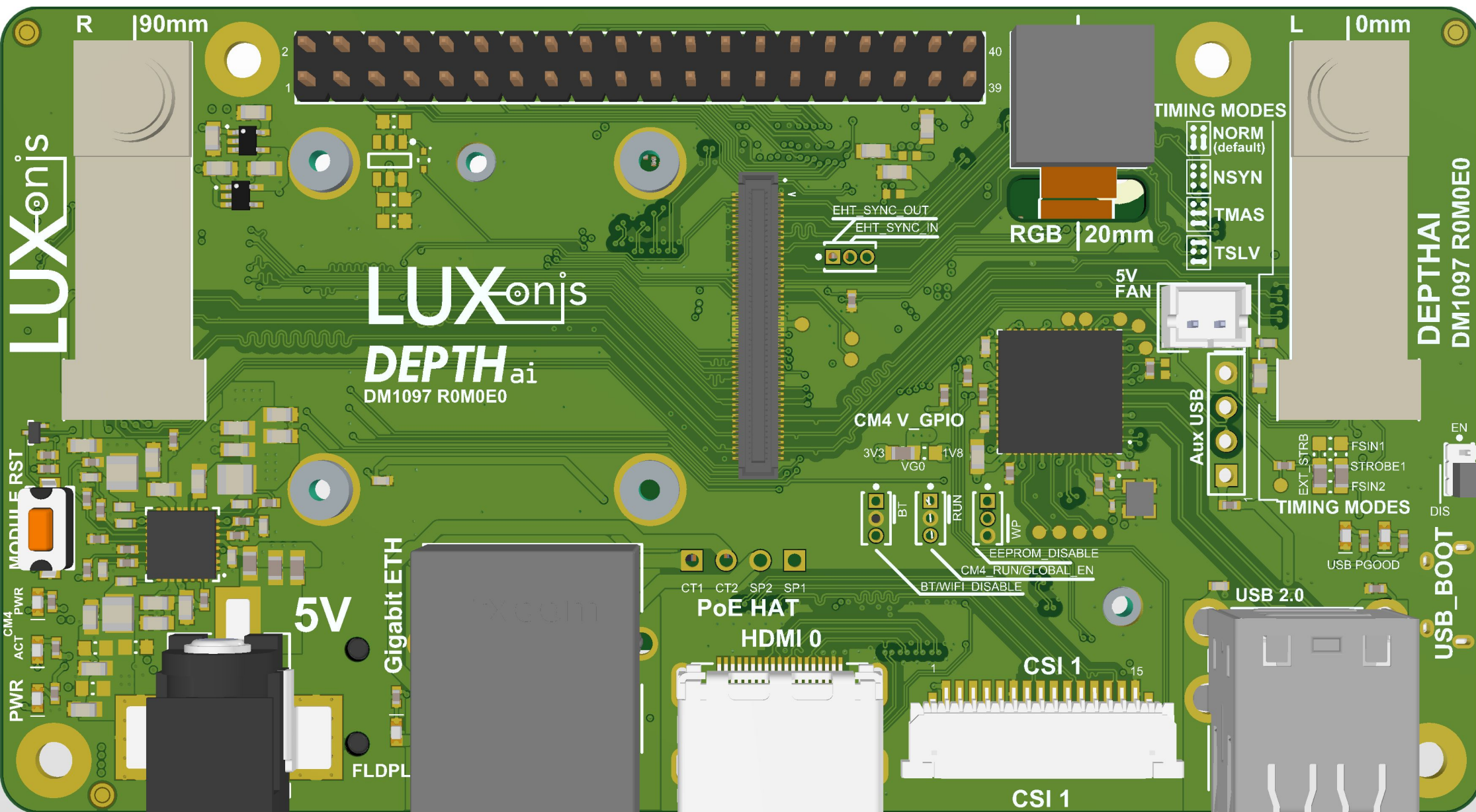
2

E

[Variant: [All Variants]]: View from Bottom side (Scale 2)

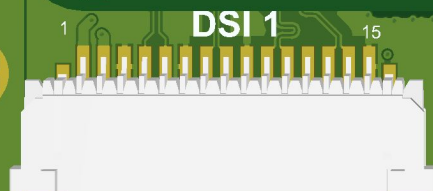
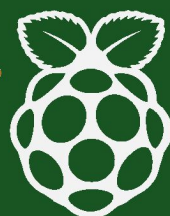


Title: <b>DM1097</b>		
Number: D0000200	Revision: ROM0 E0	
Date: 7. 01. 2021	Sheet: 3 of 3	PROPRIETARY AND CONFIDENTIAL
Drawn by: David Malovrh		THE INFORMATION CONTAINED IN THIS DRAWING IS THE SOLE PROPERTY OF LUXONIS HOLDING CORPORATION. ANY REPRODUCTION IN PART OR AS A WHOLE WITHOUT THE WRITTEN PERMISSION IS PROHIBITED.





**LUX**onjs  
**DEPTH**ai  
DM1097 R0M0E0



DSI 1

AUX IO SPI

3.3V SD

AUDIO

uSD card  
Used only for CM4 Lite